

# SOT825-1

plastic low profile fine-pitch ball grid array package; 183 balls; body 12 x 12 x 1.05 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	LFPGA183
<b>Package type industry code</b>	LFPGA183
<b>Package style descriptive code</b>	LFPGA (low profile fine-pitch ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-205
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	14-7-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	11.9	-	12	12.1	mm
E	package width	11.9	-	12	12.1	mm
A	seated height	[tbd]	-	1.6	1.6	mm
A <sub>2</sub>	package height	0.95	-	1.05	1.2	mm
n <sub>2</sub>	actual quantity of termination	-	-	183	-	



## 2. Package outline

LFBGA183: plastic low profile fine-pitch ball grid array package; 183 balls; body 12 x 12 x 1.05 mm SOT825-1

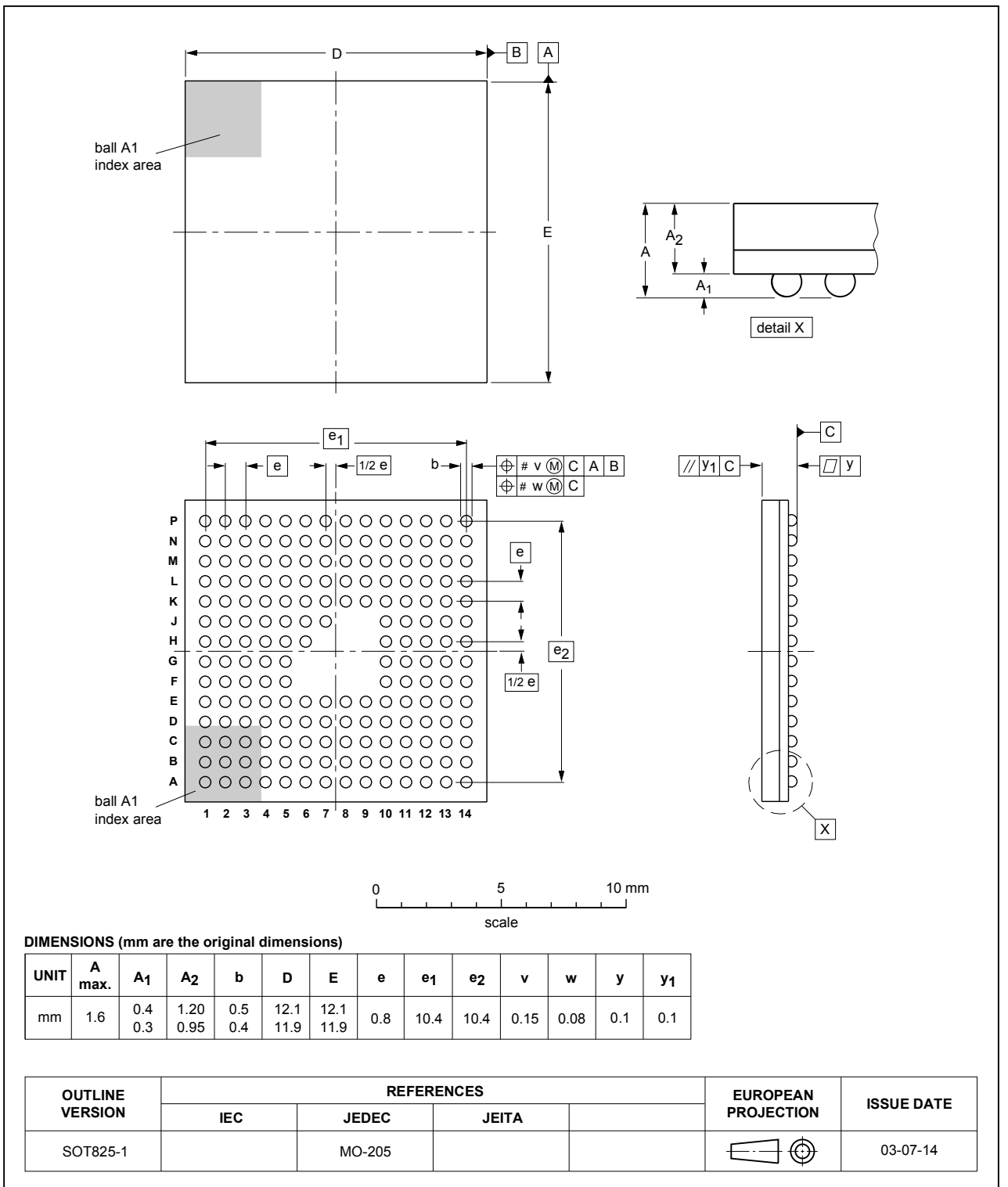
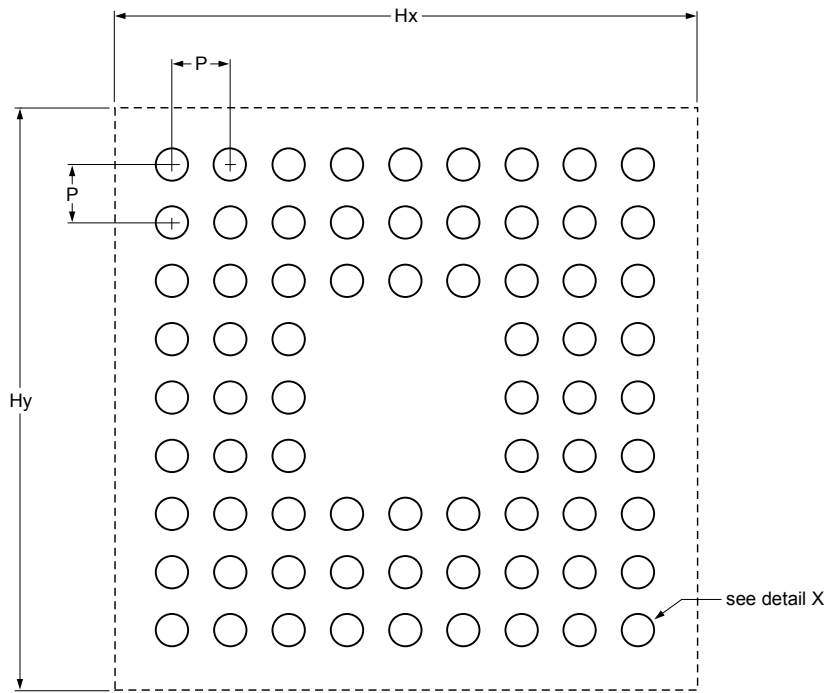


Fig. 1. Package outline LFBGA183 (SOT825-1)




### 3. Soldering

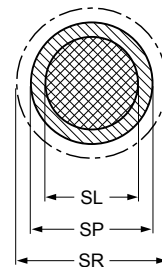
Footprint information for reflow soldering of LFBGA183 package

SOT825-1



Generic footprint pattern  
Refer to the package outline drawing for actual layout

-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area
- solder resist



detail X

DIMENSIONS in mm

P	SL	SP	SR	Hx	Hy
0.80	0.330	0.400	0.480	12.575	12.575

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Fig. 2. Reflow soldering footprint for LFBGA183 (SOT825-1)

## 4. Legal information

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